MSKSEMI 美森科













ESD

TSS

MOV

GDT

PLED

MSESD36VD5B

Product specification





General description

The MSESD36VD5B is designed to protect voltage sensitive components from ESD and transient voltage events. Excell ent clamping capability, low leakage, and fast response tim e, make these parts ideal for ESD protection on designs where board space is at a premium

Features and benefits

- Reverse stand-off voltage: 36V Max
- Low leakage current: nA Level
- Low Clamping Voltage
- Response time is typically < 1 ns
- IEC61000-4-2 Level 4 ESD Protection

Application information

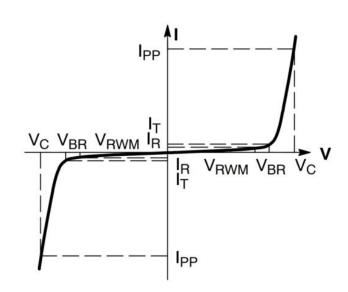
- Cell phones
- Audio equipment
- Portable devices
- Digital cameras
- Power supplies

Reference News

SOD-523	Graphic symbol	Marking		
Hill State of the Control of the Con		36X		

Portion Electronics Parameter

Symbol	Parameter
I _{PP}	Maximum Reverse Peak Pulse Current
Vc	Clamping Voltage @ IPP
VRWM	Working Peak Reverse Voltage
lR	Maximum Reverse Leakage Current @ V _{RWM}
lτ	Test Current
V_{BR}	VBR Breakdown Voltage @ I _T





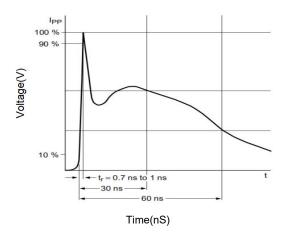
Maximum Ratings ($T_{OP} = 25^{\circ}C$, unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (tp = 8/20µs)	P _{PPM}	500	W
Peak Pulse Current (tp = 8/20μs)	I _{PPM}	8	А
Maximum lead temperature for soldering during 10s	T∟	260	°C
Storage Temperature Range	T_{stg}	-55 to +150	°C
Operating Temperature Range	T _{OP}	-40 to +125	°C
Maximum junction temperature	T _i	150	°C
ESD voltage IEC 61000-4-2 (air discharge)	V _{ESD}	30	kV
ESD voltage IEC 61000-4-2 (contact discharge)	V _{ESD}	30	kV

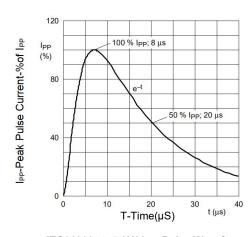
Electrical Characteristics (T_{OP} = 25°C, unless otherwise specified)

Parameter	Symbol	Min	Тур	Max	Unit	Condition
Reverse Working Voltage	V_{RWM}			36.0	V	
Breakdown Voltage	V_{BR}	38.0		44.0	V	ե=1mA
Leakage Current ILeak	l _R			100	nA	V _{RWM} =36V
Clamping Voltage	Vc		45	50	V	l₀=1A,Tp=8/20μs
Clamping Voltage	Vc		56	62	V	l₀=8A,Tp=8/20μs
Junction Capacitance	C₁		20	30	pF	V _R =0V, f=1MHz

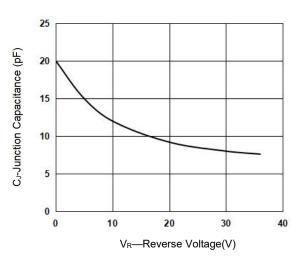
TypicalPerformanceCharacteristics (T_A=25 °C unless otherwise Specified)



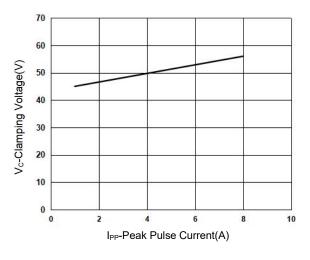
IEC61000-4-2 Pulse Waveform



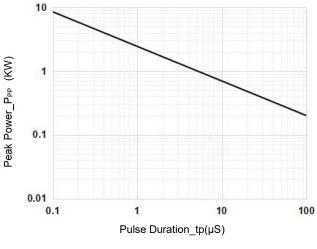
IEC61000-4-5 8X20μs Pulse Waveform



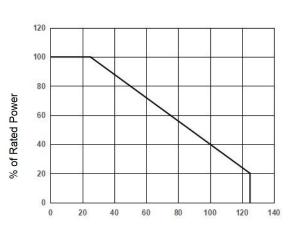
Junction Capacitance vs. Reverse Voltage



Clamping Voltage vs. Peak Pulse Current



Peak Pulse Power vs. Pulse Time

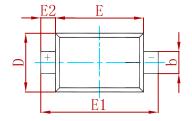


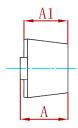
Ambient Temperature_Ta(°C)

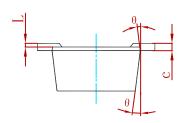
Power Derating Curve



PACKAGE MECHANICAL DATA

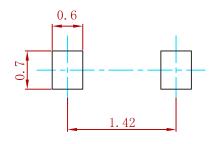






Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Зушьог	Min	Max	Min	Max	
Α	0.510	0.770	0.020	0.031	
A1	0.500	0.700	0.020	0.028	
b	0.250	0.350	0.010	0.014	
С	0.080	0.150	0.003	0.006	
D	0.750	0.850	0.030	0.033	
Е	1.100	1.300	0.043	0.051	
E1	1.500	1.700	0.059	0.067	
E2	0.200 REF		0.008 REF		
L	0.010	0.070	0.001	0.003	
θ	7° REF		7° F	REF	

Suggested Pad Layout



Note:

- 1. Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
MSESD36VD5BC	SOD-523	3000



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